

NOTES:

1. MATERIAL:

- 1.1 Housing: High Temperature Thermoplastic UL94V-0; Color Black.
- 1.2 Contact: Copper Alloy, T=0.10mm.
- 1.3 Shell: Stainless Steel, T=0.12mm.
- 1.4 Crank: Stainless Steel, T=0.40mm

2. FINISH:

- 2.1 Contact: Plated Gold Over all
Underplated Nickel Over all
- 2.2 Shell: Plated Gold on the Solder Tails,
Underplated Nickel Over all

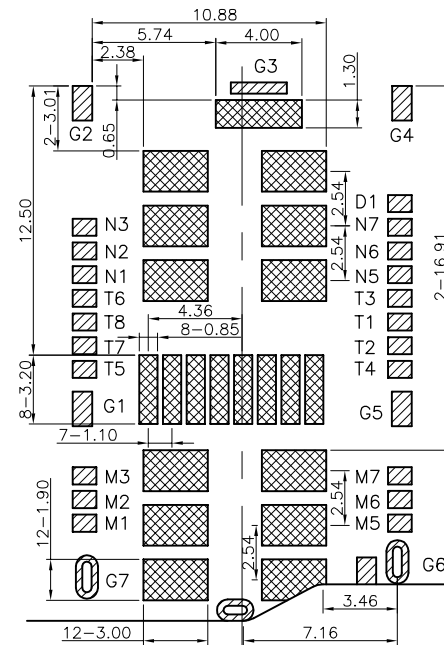
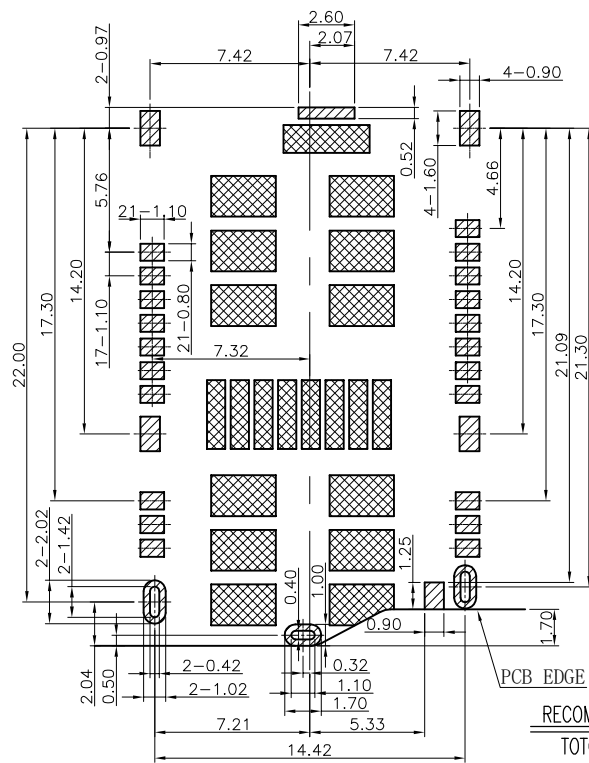
3. SPECIALITY:

- 3.1 Rated current: 0.5A
- 3.2 Rated voltage: 30V
- 3.3 Contact Resistance: 100mΩ MAX
- 3.4 Insulation Resistance: 100MΩ MIN
- 3.5 Dielectric withstanding voltage: 100V AC.
- 3.6 Solder ability: 245±5°C, 5±0.5s.
- 3.7 Durability: 1000 Cycles Min.
- 3.8 Operating condition: Temperature: -30°C~+80°C
Humidity: 80% R.H MAX



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TOLERANCE: XX ±0.30 XXX ±0.25 XXXX ±0.15 X° ±2° X.X° ±0.5°	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: 1.35H 三选二卡座 (DOUBLE NANO SIM CARD OR TF CARD)
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC37-3IN121-135B
UNIT: mm [inch] SCALE: 1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-IN17032117
			SHEET NO. 1 OF 1



RECOMMENDED PCB LAYOUT

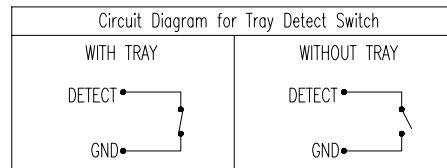
TOLERANCE ±0.03

▨ THESE AREA SHOULD BE FREE OF ANY CONDUCTIVE TRACES

▩ SMT SOLDER AREA

SIM CARD PIN NO.	DESCRIPTION	T-CARD PIN NO.	DESCRIPTION
N1/M1	VCC	T1	DAT2
N2/M2	RST	T2	CD/DAT3
N3/M3	CLK	T3	CMD
N5/M5	GND	T4	VDD
N6/M6	VPP	T5	CLK
N7/M7	I/O	T6	VSS
D1	DETECT	T7	DATO
		T8	DAT1

G1-G7	GND
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UNIT: mm [inch]

SCALE:1:1

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PART NAME:

1.35H 三选二卡座 (DOUBLE NANO SIM CARD OR TF CARD)

PART NO.

HYCW37-3IN121-135B

MOLD NO.

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1 OF 1